

Overview

KEMET's U2J dielectric features a maximum operating temperature of 125°C and is considered stable. The

is suited for resonant circuit applications or those where Q and stability of capacitance characteristics are required. U2J is an extremely stable dielectric material that exhibits a negligible shift in capacitance with respect to voltage and boasts a predictable and linear change in capacitance with reference to ambient temperature with no aging

effect. In addition, U2J dielectric extends the available capacitance range of Class I MLCCs to achieve values previously only available using Class II dielectric materials like X7R, X5R, Y5V and Z5U. U2J is not sensitive to DC Bias as compared to Class II dielectric materials and retains over 99% of nominal capacitance at full rated voltage. Capacitance change is limited to -750 ± 120 ppm /°C from -55°C to $+125^{\circ}\text{C}$. These devices are Lead-free, RoHS and REACH compliant without exception and are capable of withstanding multiple passes through a Lead-free solder reflow profile.

Benefits

- Low dissipation factor DF < 0.1%
- Low noise solution similar to COG
- Low ESR and ESL
- High thermal stability
- High ripple current capability
- Preferred capacitance solution at line frequencies and into the MHz range
- Retains over 99% of nominal capacitance at full rated voltage
- Small predictable and linear capacitance change with respect to temperature
- Operating temperature range of -55°C to $+125^{\circ}\text{C}$



Ordering Information

C	1206	C	104	J	3	J	A	C	TU
Ceramic	Case Size (L" x W")	Specification/ Series ¹	Capacitance Code (pF)	Capacitance Tolerance ²	Rated Voltage (VDC)	Dielectric	Failure Rate/ Design	Termination Finish ³	Packaging/ Grade (C-Spec)
	0402 0603 0805 1206 1210 1812	C = Standard	Two significant digits + number of zeros.	F = $\pm 1\%$ G = $\pm 2\%$ J = $\pm 5\%$ K = $\pm 10\%$ M = $\pm 20\%$	8 = 10 4 = 16 3 = 25 5 = 50	J = U2J	A = N/A	C = 100% Matte Sn	See "Packaging C-Spec Ordering Options Table" below

¹ Flexible termination option is available. Please see FT-CAP product bulletin C1062_COG_FT-CAP_SMD

² Additional capacitance tolerance offerings may be available. Contact KEMET for details.

Packaging C-Spec Ordering Options Table

Packaging Type ¹	Packaging/Grade Ordering Code (C-Spec)
Bulk Bag/Unmarked	Not required (Blank)
7" Reel/Unmarked	TU
13" Reel/Unmarked	7411 (EIA 0603 and smaller case sizes) 7210 (EIA 0805 and larger case sizes)
7" Reel/Unmarked/2 mm pitch ²	7081
13" Reel/Unmarked/2 mm pitch ²	7082

¹ Default packaging is "Bulk Bag". An ordering code C-Spec is not required for "Bulk Bag" packaging.

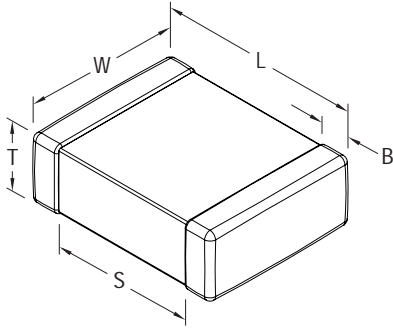
¹ The terms "Marked" and "Unmarked" pertain to laser marking option of capacitors. All packaging options labeled as "Unmarked" will contain capacitors that have not been laser marked. The option to laser mark is not available on these devices. For more information see "Capacitor Marking".

² The 2 mm pitch option allows for double the packaging quantity of capacitors on a given reel size. This option is limited to EIA 0603 (1608 metric) case size devices. For more information regarding 2 mm pitch option see "Tape & Reel Packaging Information".

Benefits cont'd

- Capacitance up to 470 nF
 - DC voltage ratings up to 50 V
 - Lead (Pb)-free, RoHS and REACH compliant
 - Non-polar device, minimizing installation concerns
 - 100% pure
-
-
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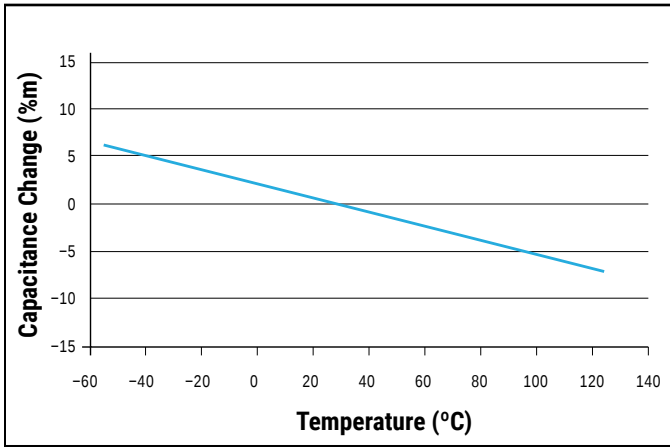
Dimensions – Millimeters (Inches)



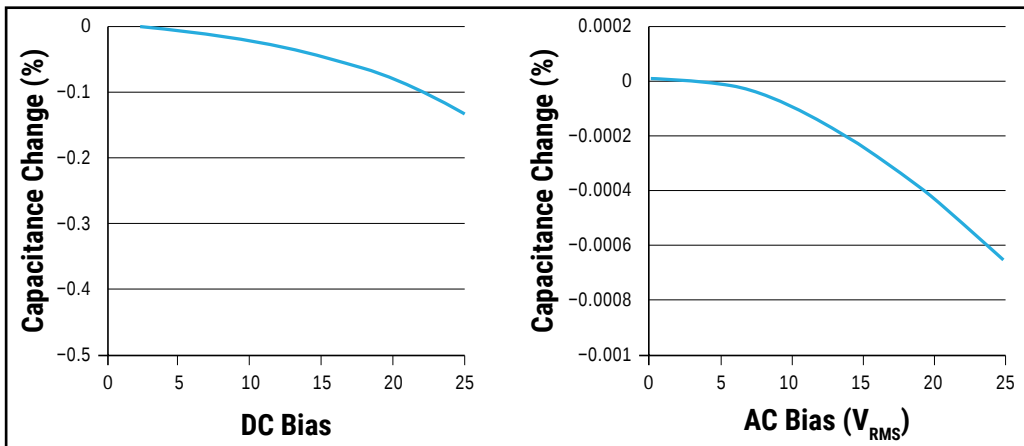
EIA Size Code	Metric Size Code	L					

Electrical Characteristics (Typical)

Capacitance vs. Temperature (TCC)



DC & AC Bias Effective Capacitance



Post Environmental Limits

High Temperature Life, Biased Humidity, Moisture Resistance					
Dielectric	Rated DC Voltage	Capacitance Value	Dissipation Factor (Maximum %)	Capacitance Shift	Insulation Resistance
U2J	All	All	0.5	0.3% or ± 0.25 pF	10% of Initial Limit

Table 1A – Capacitance Range/Selection Waterfall (0402 – 1812 Case Sizes)

Case Size	Capacitance Range	Selection					
		0.01	0.02	0.05	0.1	0.2	0.5
0402	100pF - 10nF						
0603	100pF - 10nF						
0805	100pF - 10nF						
1206	100pF - 10nF						
1608	100pF - 10nF						
1812	100pF - 10nF						

Table 1A – Capacitance Range/Selection Waterfall (0402 – 1812 Case Sizes) cont'd

Table 2A – Chip Thickness/Tape & Reel Packaging Quantities

Thickness Code	Case Size ¹	Thickness ± Range (mm)	Paper Quantity ¹		Plastic Quantity	
			7" Reel	13" Reel	7" Reel	13" Reel
BB	0402	0.50 ± 0.05	10,000	50,000	0	0
CF	0603	0.80 ± 0.07*	4,000	15,000	0	0
DN	0805	0.78 ± 0.10*	4,000	15,000	0	0
DP	0805	0.90 ± 0.10*	4,000	15,000	0	0
DG	0805	1.25 ± 0.15	0	0	2,500	10,000
EB	1206	0.78 ± 0.10	4,000	10,000	4,000	10,000
EC	1206	0.90 ± 0.10	0	0	4,000	10,000
EE	1206	1.10 ± 0.10	0	0	2,500	10,000
EF	1206	1.20 ± 0.15	0	0	2,500	10,000
EH	1206	1.60 ± 0.20	0	0	2,000	8,000
FB	1210	0.78 ± 0.10	0	0	4,000	10,000
FC	1210	0.90 ± 0.10	0	0	4,000	10,000
FE	1210	1.00 ± 0.10	0	0	2,500	10,000
FG	1210	1.25 ± 0.15	0	0	2,500	10,000
FH	1210	1.55 ± 0.15	0	0	2,000	8,000
FM	1210	1.70 ± 0.20	0	0	2,000	8,000
GB	1812	1.00 ± 0.10	0	0	1,000	4,000
GC	1812	1.10 ± 0.10	0	0	1,000	4,000
GH	1812	1.40 ± 0.15	0	0	1,000	4,000
GK	1812	1.60 ± 0.20	0	0	1,000	4,000
Thickness Code	Case Size ¹	Thickness ± Range (mm)	7" Reel	13" Reel	7" Reel	13" Reel
			Paper Quantity ¹		Plastic Quantity	

Package quantity based on finished chip thickness specifications.

¹ If ordering using the 2 mm Tape and Reel pitch option, the packaging quantity outlined in the table above will be doubled. This option is limited to EIA 0603 (1608 metric) case size devices. For more information regarding 2 mm pitch option see "Tape & Reel Packaging Information".

Table 2B – Bulk Packaging Quantities

Packaging Type		Loose Packaging	
		Bulk Bag (default)	
Packaging C-Spec ¹		N/A ²	
Case Size		Packaging Quantities (pieces/unit packaging)	
EIA (in)	Metric (mm)	Minimum	Maximum
0402	1005	1	50,000
0603	1608		
0805	2012		
1206	3216		
1210	3225		
1812	4532		20,000

¹ The "Packaging C-Spec" is a 4 to 8 digit code which identifies the packaging type and/or product grade. When ordering, the proper code must be included in the 15th through 22nd character positions of the ordering code. See "Ordering Information" section of this document for further details. Commercial Grade product ordered without a packaging C-Spec will default to our standard "Bulk Bag" packaging. Contact KEMET if you require a bulk bag packaging option for Automotive Grade products.

² A packaging C-Spec (see note 1 above) is not required for "Bulk Bag" packaging (excluding Anti-Static Bulk Bag and Automotive Grade products). The 15th through 22nd character positions of the ordering code should be left blank. All product ordered without a packaging C-Spec will default to our standard "Bulk Bag" packaging.

Table 3 – Chip Capacitor Land Pattern Design Recommendations per IPC-7351

EIA Size Code	Metric Size Code															

Soldering Process

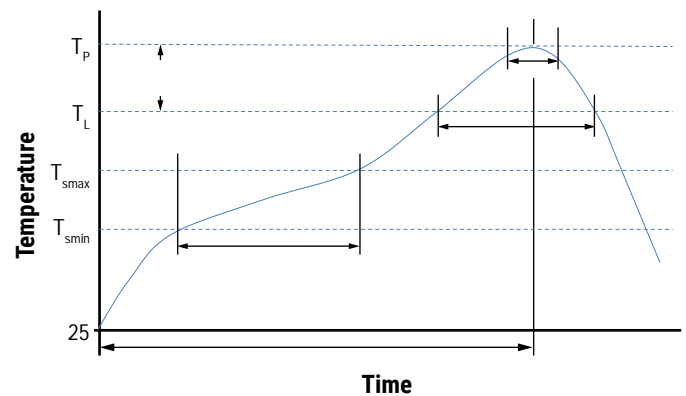
Recommended Soldering Technique:

- Solder wave or solder reflow for EIA case sizes 0603, 0805 and 1206
- All other EIA case sizes are limited to solder reflow only

Recommended Reflow Soldering Profile:

KEMET's families of surface mount multilayer ceramic capacitors (SMD MLCCs) are compatible with wave (single or dual), convection, IR or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020 standard for moisture sensitivity testing. These devices can safely withstand a maximum of three reflow passes at these conditions.

Profile Feature	Termination Finish	
	SnPb	100% Matte Sn
Preheat/Soak		
Temperature Minimum (T_{Smin})	100°C	150°C
Temperature Maximum (T_{Smax})	150°C	200°C
Time (t_s) from T_{Smin} to T_{Smax}	60 – 120 seconds	60 – 120 seconds
Ramp-Up Rate (T_L to T_P)	3°C/second maximum	3°C/second maximum
Liquidous Temperature (T_L)	183°C	217°C
Time Above Liquidous (t_L)	60 – 150 seconds	60 – 150 seconds
Peak Temperature (T_P)	235°C	260°C
Time Within 5°C of Maximum Peak Temperature (t_p)	20 seconds maximum	30 seconds maximum
Ramp-Down Rate (T_P to T_L)	6°C/second maximum	6°C/second maximum
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum



Note 1: All temperatures refer to the center of the package, measured on the capacitor body surface that is facing up during assembly reflow.

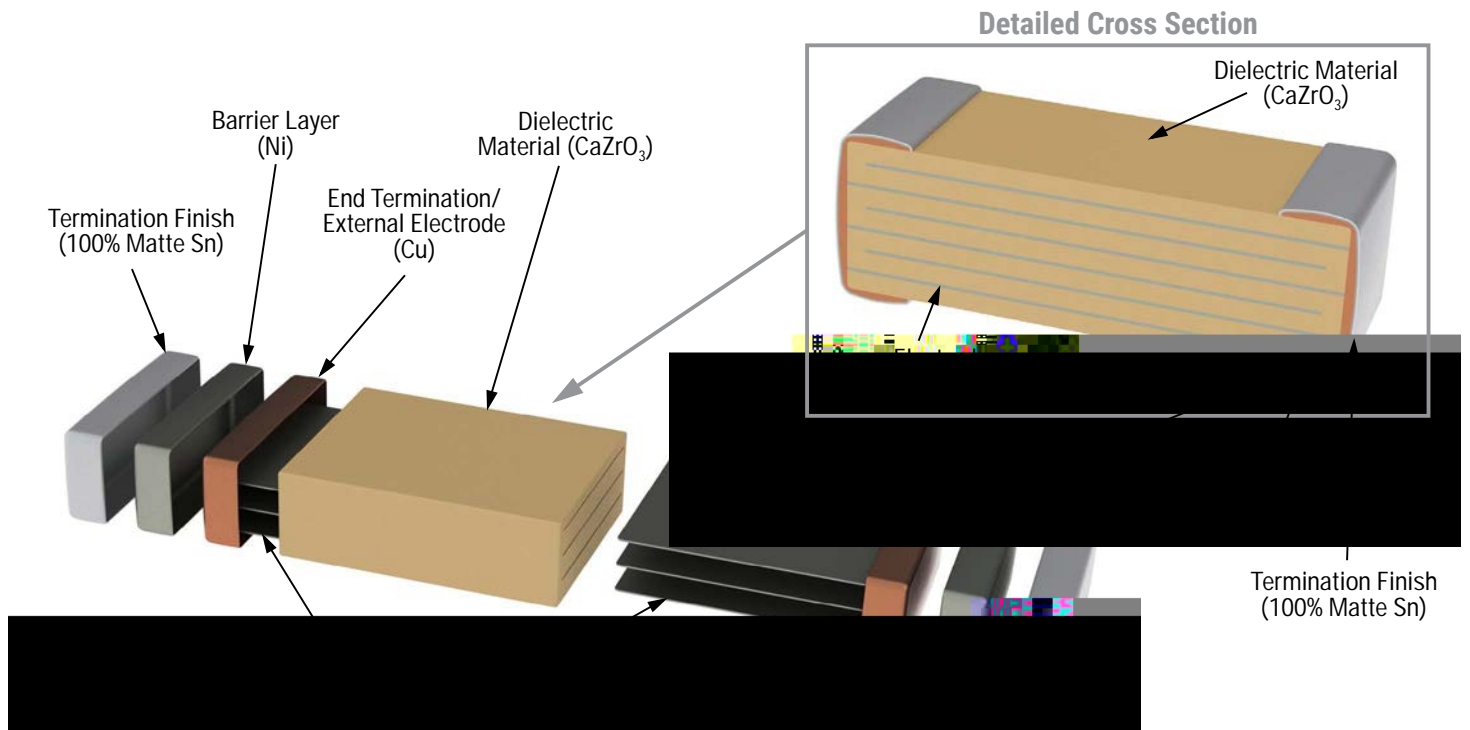
Table 4 – Performance & Reliability: Test Methods and Conditions

Stress	Reference	Test or Inspection Method									
		Package Size (L" x W")	Force	Duration							
Terminal Strength	JIS-C-6429	Appendix 1, Note:	<table border="1"> <tr> <td>0402</td> <td>5 N (0.51 kg)</td> <td rowspan="3">60 seconds</td> </tr> <tr> <td>0603</td> <td>10 N (1.02 kg)</td> </tr> <tr> <td>≥ 0805</td> <td>18 N (1.83 kg)</td> </tr> </table>		0402	5 N (0.51 kg)	60 seconds	0603	10 N (1.02 kg)	≥ 0805	18 N (1.83 kg)
0402	5 N (0.51 kg)	60 seconds									
0603	10 N (1.02 kg)										
≥ 0805	18 N (1.83 kg)										
Board Flex	JIS-C-6429	Appendix 2, Note: 3.0 mm (minimum).									
Solderability	J-STD-002	Magnification 50 X Conditions:									
		a) Method B, 4 hours at 155°C, dry heat at 235°C									
		b) Method B at 215°C category 3									
		c) Method D, category 3 at 260°C									
Temperature Cycling	JESD22 Method JA-104	1,000 cycles (-55°C to +125°C). Measurement at 24 hours +/- 4 hours after test conclusion.									
Biased Humidity	MIL-STD-202 Method 103	Load Humidity: 1,000 hours 85°C/85% RH and rated voltage. Add 100 K ohm resistor. Measurement at 24 hours +/- 4 hours after test conclusion.									
		Low Volt Humidity: 1,000 hours 85°C/85% RH and 1.5 V. Add 100 K ohm resistor. Measurement at 24 hours +/- 4 hours after test conclusion.									
Moisture Resistance	MIL-STD-202 Method 106	t = 24 hours/cycle. Steps 7a & 7b not required. Measurement at 24 hrs. +/- 4 hours after test conclusion.									
Thermal Shock	MIL-STD-202 Method 107	-55°C/+125°C. Note: Number of cycles required – 300. Maximum transfer time – 20 seconds. Dwell time – 15 minutes. Air – Air.									
High Temperature Life	MIL-STD-202 Method 108/EIA -198	1,000 hours at 125°C with 2 X rated voltage applied.									
Storage Life	MIL-STD-202 Method 108	125°C, 0 VDC for 1,000 hours.									
Vibration	MIL-STD-202 Method 204	5 G's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8" X 5" PCB 0.031" thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10 – 2,000 Hz									
Mechanical Shock	MIL-STD-202 Method 213	Figure 1 of Method 213, Condition F.									
Resistance to Solvents	MIL-STD-202 Method 215	Add aqueous wash chemical, OKEM clean or equivalent.									

Storage and Handling

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature—reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 70% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within 1.5 years of receipt.

Construction



Capacitor Marking (Optional):

Laser marking option is not available on:

- C0G, U2J, Ultra Stable X8R, and Y5V dielectric devices
- EIA 0402 case size devices
- EIA 0603 case size devices with Flexible Termination option.
- K

Tape & Reel Packaging Information

KEMET offers multilayer ceramic chip capacitors packaged in 8, 12 and 16 mm tape on 7" and 13" reels in accordance with EIA Standard 481. This packaging system is compatible with all tape-fed automatic pick and place systems. See Table 2 for details on reeling quantities for commercial chips.

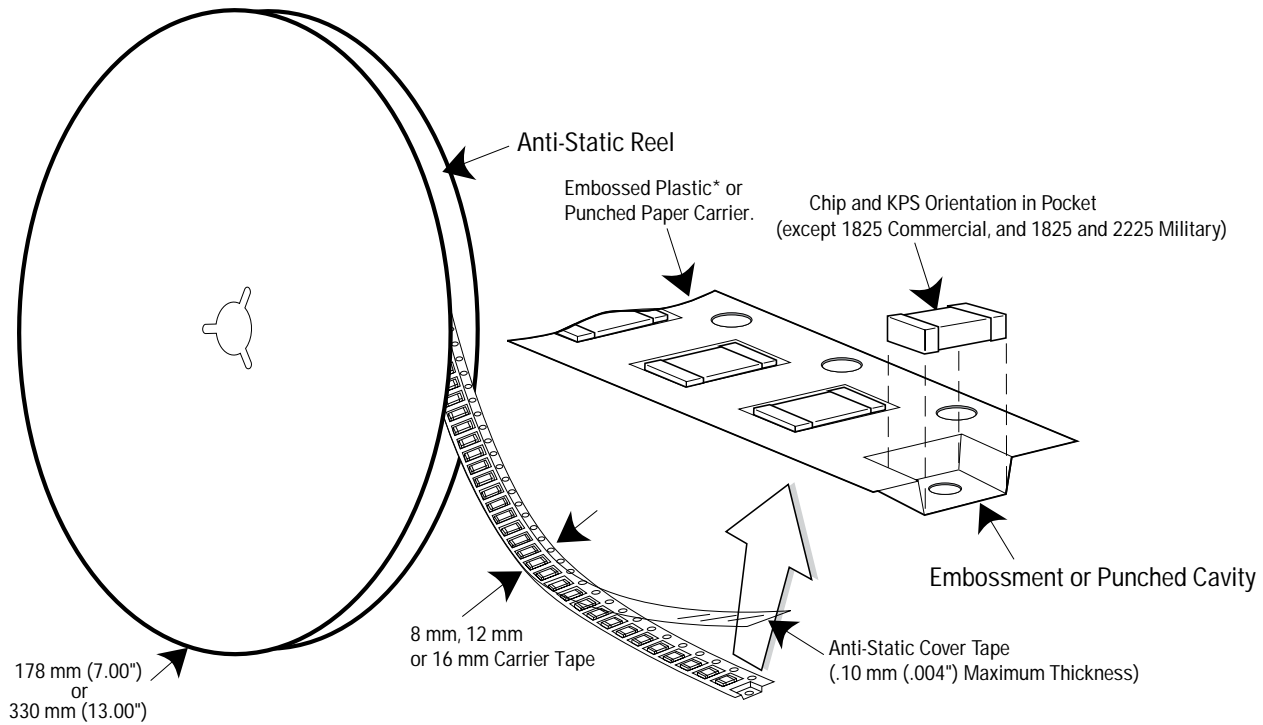


Figure 1 – Embossed (Plastic) Carrier Tape Dimensions

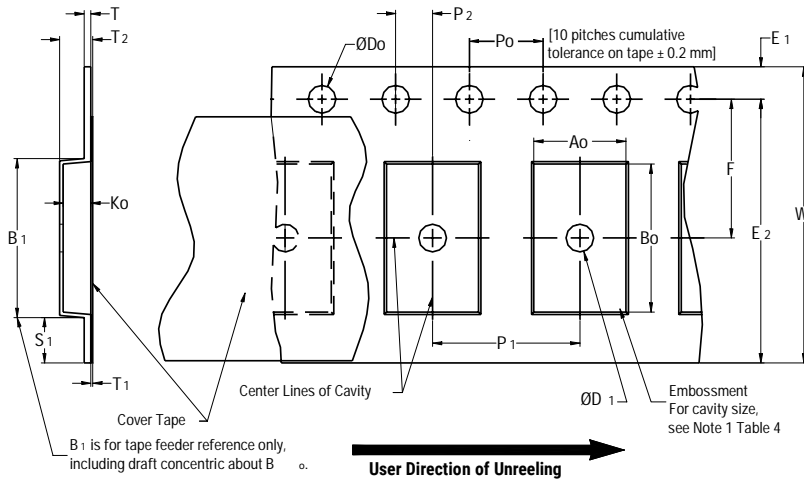


Table 6 – Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

Figure 2 – Punched (Paper) Carrier Tape Dimensions

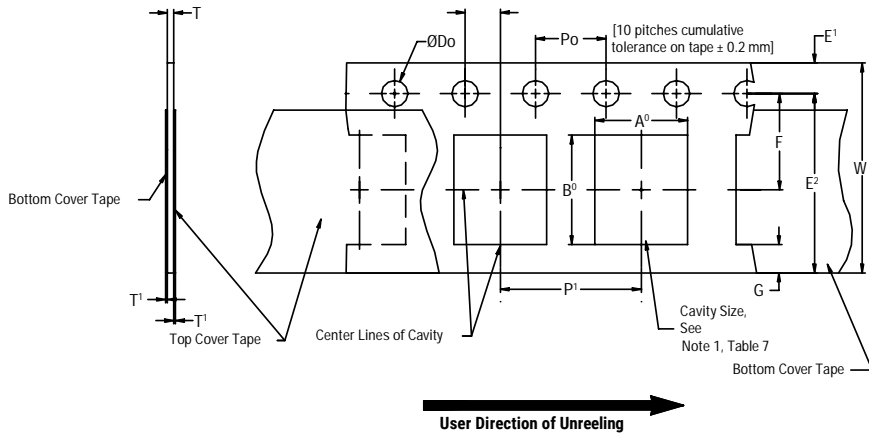


Table 7 – Punched (Paper) Carrier Tape Dimensions

Metric will govern

Constant Dimensions – Millimeters (Inches)							
Tape Size	D_0	E_1	P_0	P_2	T_1 Maximum	G Minimum	R Reference Note 2
8 mm	$1.5 +0.10 -0.0$ (0.059 +0.004 -0.0)	1.75 ± 0.10 (0.069 ±0.004)	4.0 ± 0.10 (0.157 ±0.004)	2.0 ± 0.05 (0.079 ±0.002)	0.10 (0.004) Maximum	0.75 (0.030)	25 (0.984)
Variable Dimensions – Millimeters (Inches)							
Tape Size	Pitch	E_2 Minimum	F	P_1	T Maximum	W Maximum	$A_0 B_0$
8 mm	Half (2 mm)	6.25 (0.246)	3.5 ± 0.05 (0.138 ±0.002)	2.0 ± 0.05 (0.079 ±0.002)	1.1 (0.098)	8.3 (0.327)	Note 1
8 mm	Single (4 mm)			4.0 ± 0.10 (0.157 ±0.004)			

1. The cavity defined by A_0 , B_0 and T shall surround the component with sufficient clearance that:

- a) the component

Packaging Information Performance Notes

- Cover Tape Break Force:** 1.0 Kg minimum.
- Cover Tape Peel Strength:** The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength
8 mm	0.1 to 1.0 Newton (10 to 100 gf)
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 ± 10 mm/minute.

- Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. Refer to EIA Standards 556 and 624.

Figure 3 – Maximum Component Rotation

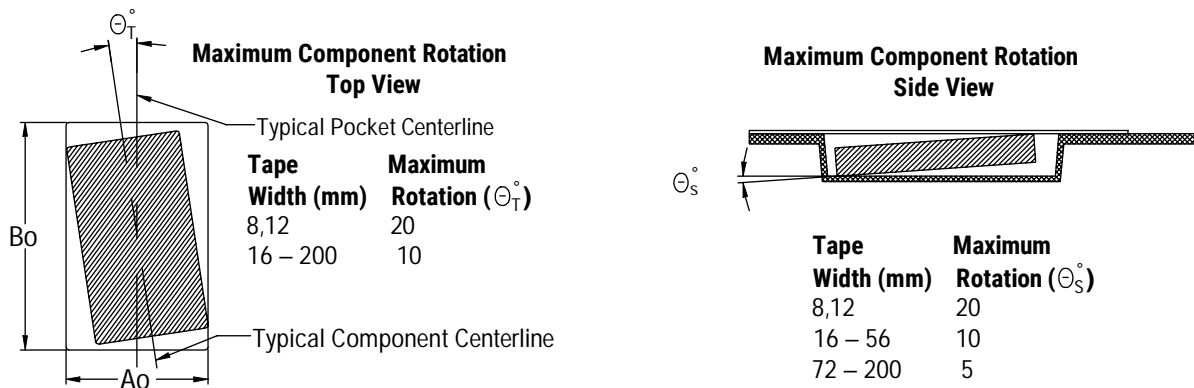


Figure 4 – Maximum Lateral Movement

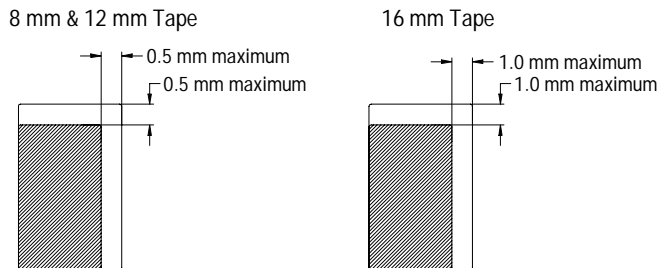


Figure 5 – Bending Radius

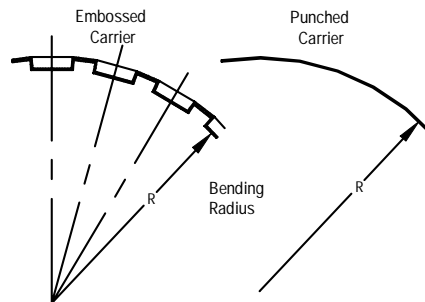
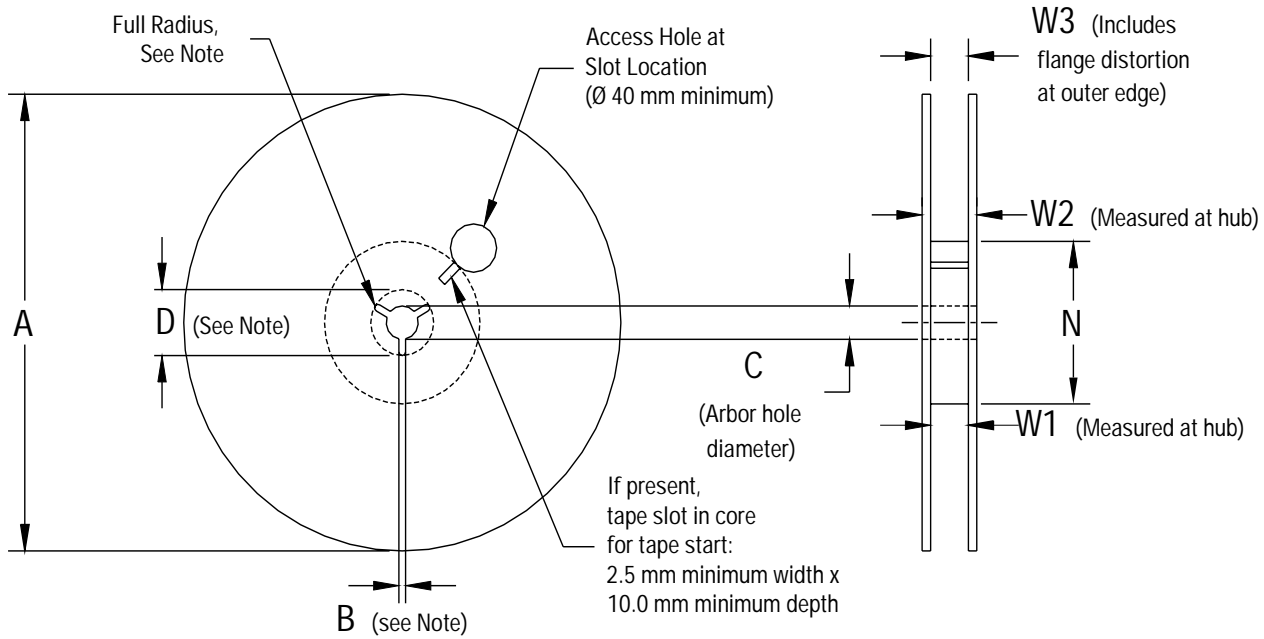


Figure 6 – Reel Dimensions



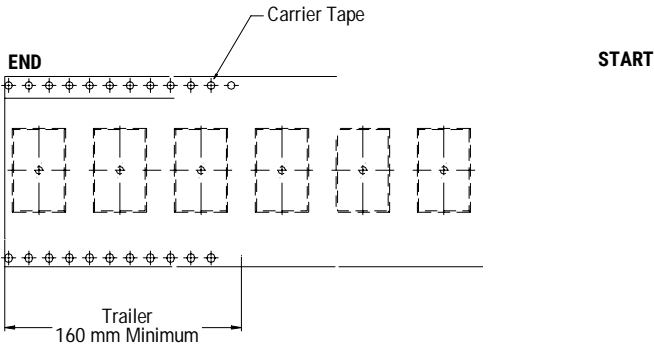
Note: Drive spokes optional; if used, dimensions B and D shall apply.

Table 8 – Reel Dimensions

Metric will govern

Constant Dimensions – Millimeters (Inches)				
Tape Size	A	B Minimum	C	D Minimum
8 mm	178 ±0.20 (7.008 ±0.008) or 330 ±0.20 (13.000 ±0.008)	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)
12 mm				
16 mm				
Variable Dimensions – Millimeters (Inches)				
Tape Size	N Minimum	W ₁	W ₂ Maximum	W ₃
8 mm	50 (1.969)	8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)	Shall accommodate tape width without interference
12 mm		12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	
16 mm		16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)	

Figure 7 – Tape Leader & Trailer Dimensions



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